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Siliup Semiconductor

SP010P80TH

-100V P-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-100V	80mΩ@10V	-20A
	98mΩ@4.5V	

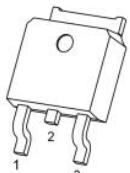
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

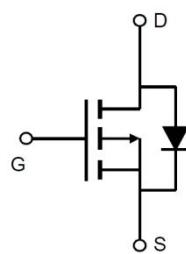
- Power switching application
- PWM Application
- DC-DC Converter

Package

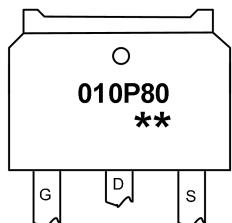


TO-252(1:G 2:D 3:S)

Circuit diagram



Marking



010P80
**

=Device Code
=Week Code



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Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	-100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current(Tc=25°C)	I _D	-20	A
Pulsed Drain Current ²	I _{DM}	-80	A
Single Pulse Avalanche Energy ³	E _{AS}	138	mJ
Total Power Dissipation ⁴ (Tc=25°C)	P _D	70	W
Thermal Resistance Junction-Case ¹	R _{θJC}	1.78	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V , ID= -250uA	-100	---	---	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} = -80V , V _{GS} =0V , TJ=25°C	---	---	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} = ±20V , V _{DS} =0V	---	---	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , ID = -250uA	-1.0	-1.7	-2.5	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	V _{GS} = -10V , ID = -15A	---	80	100	mΩ
		V _{GS} = -4.5V , ID=-15A	---	98	130	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = -50V , V _{GS} =0V , f=1MHz	---	3329	---	pF
Output Capacitance	C _{oss}		---	129	---	
Reverse Transfer Capacitance	C _{rss}		---	76	---	
Switching Characteristics						
Total Gate Charge (4.5V)	Q _g	V _{DS} = -50V , V _{GS} = -10V , ID= -15A	---	46	---	nC
Gate-Source Charge	Q _{gs}		---	9	---	
Gate-Drain Charge	Q _{gd}		---	6	---	
Turn-On Delay Time	T _{d(on)}	VDD=-50V, ID=-15A, VGS=-10V, RGEN=9.1Ω	---	15	---	ns
Rise Time	T _r		---	72	---	
Turn-Off Delay Time	T _{d(off)}		---	35	---	
Fall Time	T _f		---	56	---	
Source-Drain Diode Characteristics						
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V , IS= -1A , TJ=25°C	---	---	-1.3	V
Reverse recover time	T _{rr}	I _{SD} =-15A, di/dt=100A/us, Vdd=80, Tj=25°C	---	88	---	ns
Reverse recovery charge	Q _{rr}		---	66	---	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=50V,VGS=10V,L=0.5mH,Rg=25Ω
4. The power dissipation is limited by 150°C junction temperature



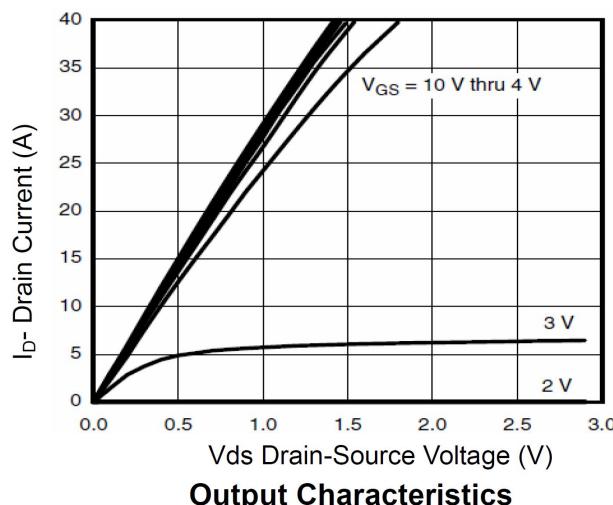
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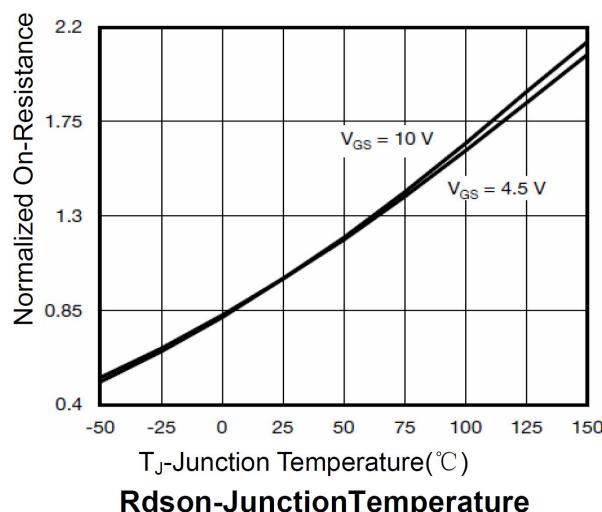
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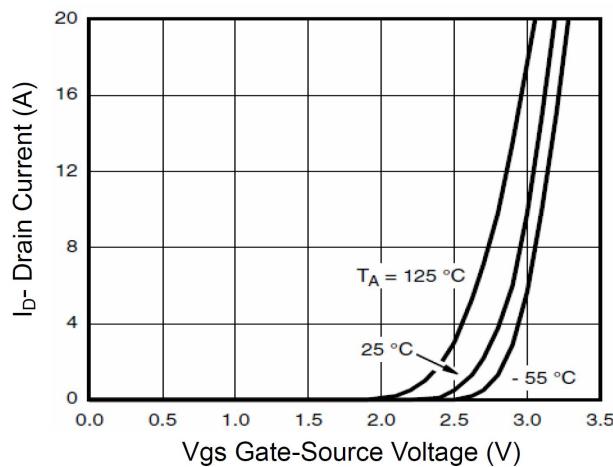
Typical Characteristics



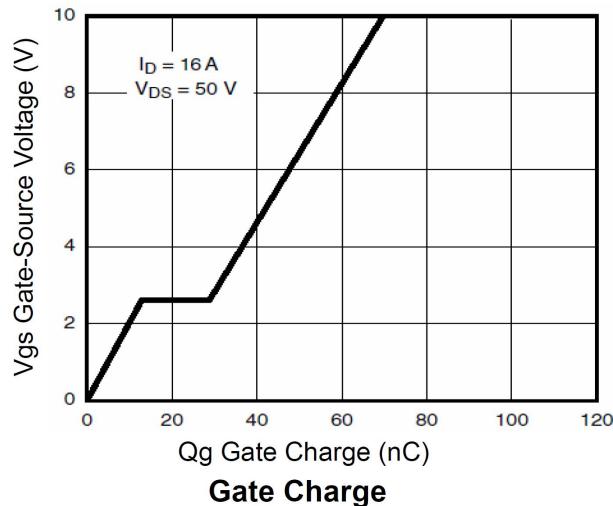
Output Characteristics



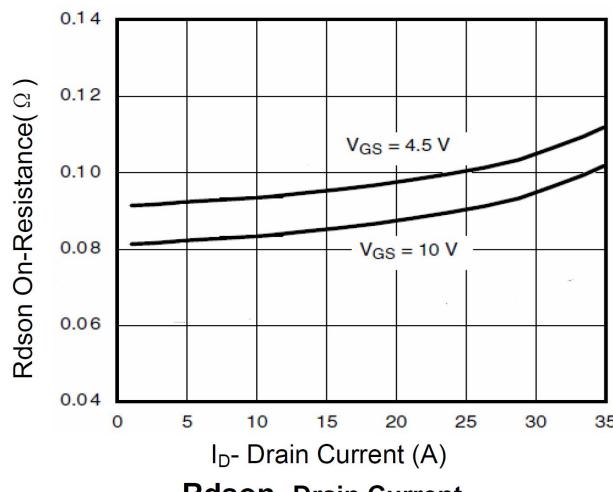
Rdson-JunctionTemperature



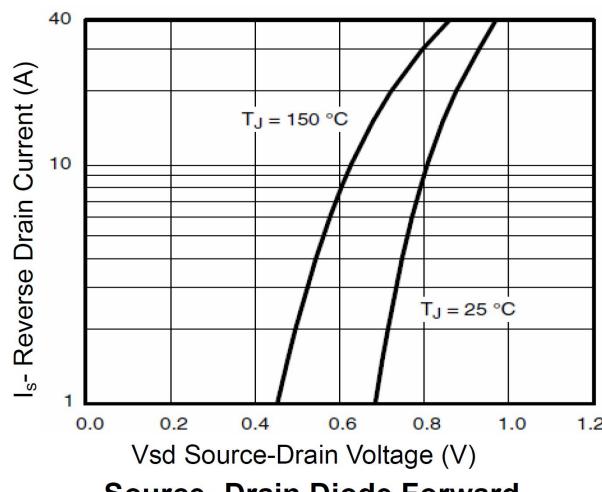
Transfer Characteristics



Gate Charge



Rdson-Drain Current



Source-Drain Diode Forward

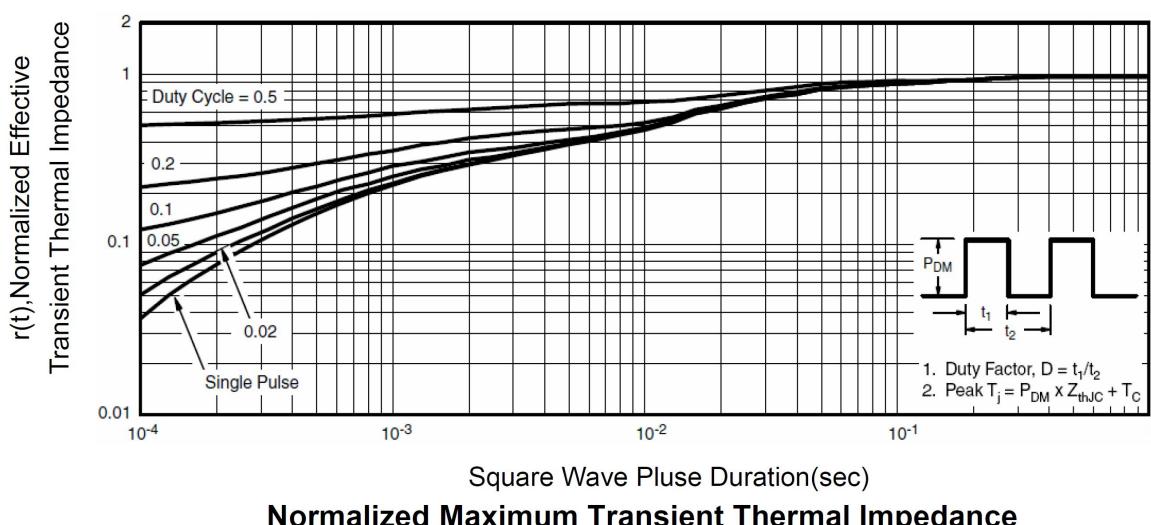
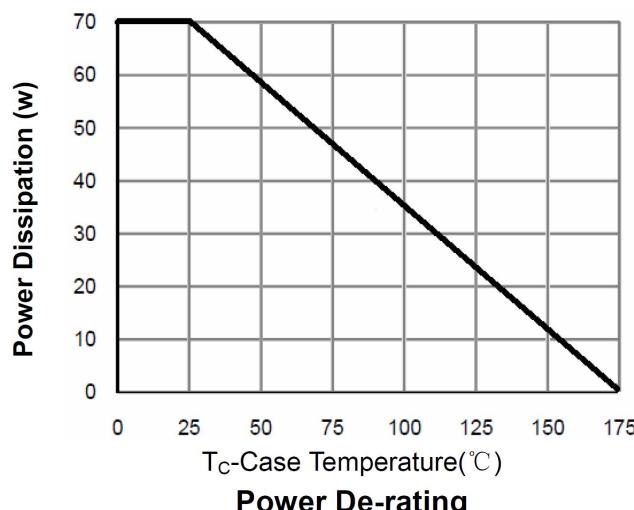
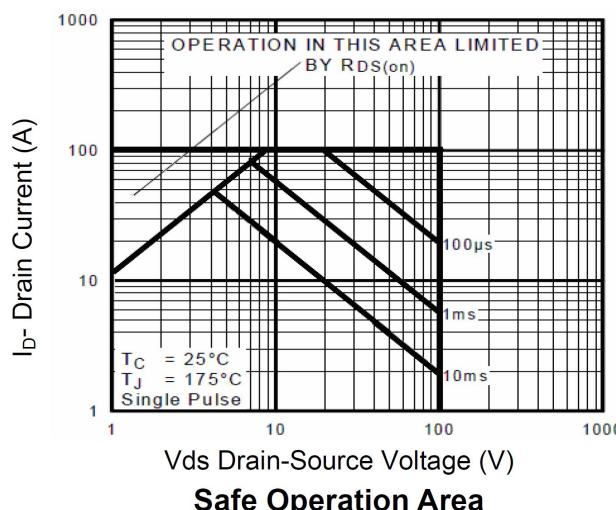
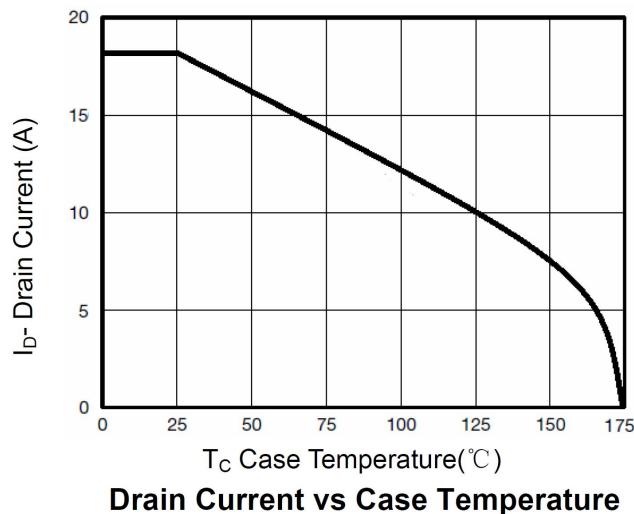
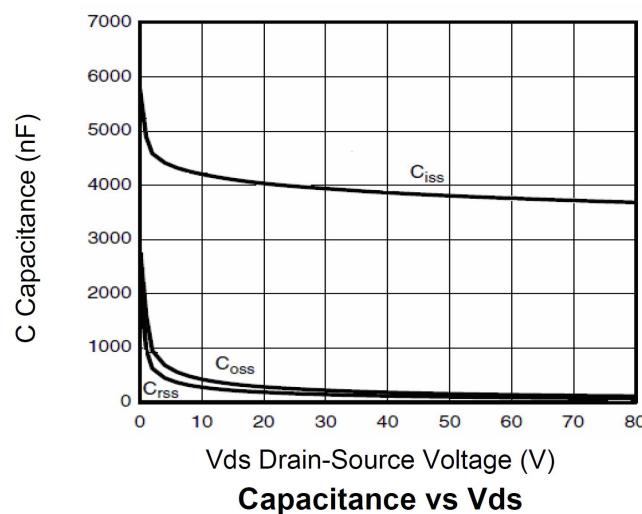


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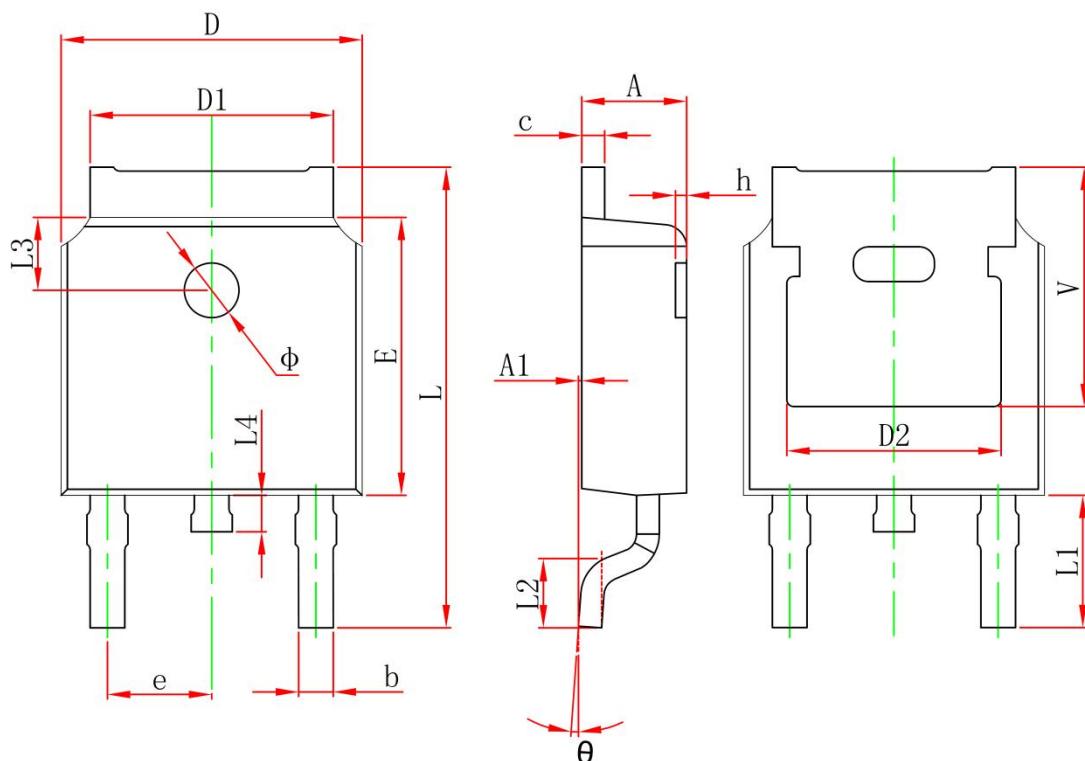
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TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
ϕ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	